

METHOD FOR PRODUCING CIRCUIT BOARD

ABSTRACT

5 Provided by the present invention is a novel method
for producing a circuit board that enables to form a
conductor circuit in a fine pattern even when an insulating
layer contains an inorganic filler. The method for
producing the circuit board includes the following steps
10 (X), (Y) and (Z):
 (X) forming a first conductor circuit on a metal layer
of a substrate with the metal layer attached thereto;
 (Y) forming a resin composition layer by using a resin
composition so as to embed the first conductor circuit
15 formed on the metal layer, and then curing the resin
composition layer to form an insulating layer; and
 (Z) removing the substrate with the metal layer
attached thereto to form a circuit board having a first
main surface in which the first conductor circuit is
20 exposed, wherein
 the resin composition includes an epoxy resin, a
curing agent and an inorganic filler.

Figure 23